

## IN THE CLAIMS

Please amend Claim 2, to read as follows.

1. (Canceled)

2. (Currently Amended) A method of manufacturing a substrate for an ink jet recording head, wherein said substrate has a supply port, penetrating said substrate, for supplying liquid and an energy generating element for generating energy for ejecting the liquid, said method comprising:

a step of forming a protecting film on a surface of said substrate which is opposite from a surface on which said energy generating element is disposed;

a step of etching a surface of said protecting film by liquid containing ammonium fluoride to make said protecting film a thin film having a thickness of not less than 100 nm and not more than 500 nm;

a step of forming an etching-resistant film on the thus etched protecting film;

a step of forming opening patterns in said protecting film and said etching-resistant film;

a step of forming an opening as said supply port, in a side of said substrate opposite from a side thereof having said energy generating element, by etching said substrate through said opening patterns;

a step of removing a projected end portion of said protecting film which is projected into said opening and which is produced in said opening forming step ~~and which~~

~~is projected into said opening formed in a side opposite from the side having said energy generating element; and~~

a step of removing said etching-resistant film after said projected end portion removing step.

3. (Original) A method according to Claim 2, wherein said substrate comprises silicon.

4. (Original) A method according to Claim 3, wherein said supply port forming step uses crystal anisotropic etching.

5. (Original) A method according to Claim 2, wherein said projected end removing step uses etching.

6. (Original) A method according to Claim 2, wherein said protecting film comprises silicon oxide.

7. (Original) A method according to Claim 2, wherein said etching-resistant film comprises polyetheramide.